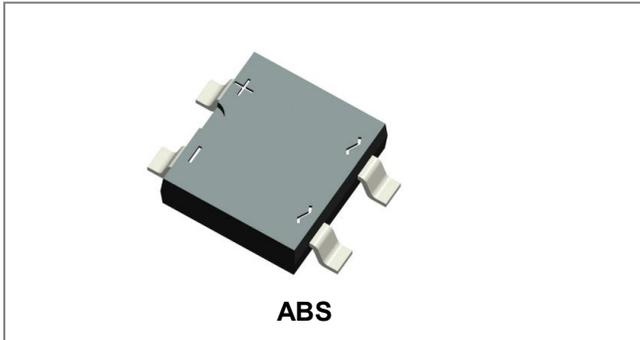


ABS2 THRU ABS10

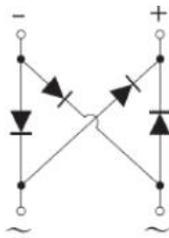
SINGLE PHASE 0.8AMP SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER



Features

- Glass passivated die construction
- Low forward voltage drop
- High current capability
- High surge current capability
- Designed for surface mount application
- Plastic material-UL flammability 94V-0
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Mechanical Data

- Case: SOPA-4, Molded plastic ABS
- Terminals: Plated leads solderable per MIL-STD-202, Method 208
- Polarity: as marked on case
- Mounting Position: Any

Maximum Ratings@T_A=25°C unless otherwise specified

Single Phase half wave 60Hz, resistive or inductive load. For capacitive load current derate by 20%.

Type Number	Symbol	ABS2	ABS4	ABS6	ABS8	ABS10	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _{DC}	200	400	600	800	1000	V
RMS Reverse Voltage	V _{RMS}	140	280	420	560	700	V
Maximum Average Rectified Output Current (Note 1)@T _A =30°C (Note 2)@T _A =30°C	I _(AV)	0.5			0.8		V
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	30					A

Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise specified

Type Number	Symbol	ABS2	ABS4	ABS6	ABS8	ABS10	Units
Maximum Forward Voltage (per element) @ $I_F=0.8\text{A}$	V_F	1.1					V
Maximum Peak Reverse Current @ $T_A = 25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A = 125^\circ\text{C}$	I_R	5.0 500					μA

* Pulse width < 300 μs , duty cycle < 2%

Thermal-Mechanical Specifications @ $T_A=25^\circ\text{C}$ unless otherwise specified

Type Number	Symbol	ABS2	ABS4	ABS6	ABS8	ABS10	Units
Typical Thermal Resistance	$R_{\theta JA}$ $R_{\theta JL}$	62.5 25					$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150					$^\circ\text{C}$

Note: 1. Mounted on glass epoxy PC board with 1.3mm² solder pad.
2. Mounted on aluminum substrate PC board with 1.3mm² solder pad.

Ratings and Characteristics Curves

FIG. 1 MAXIMUM FORWARD CURRENT DERATING CURVE

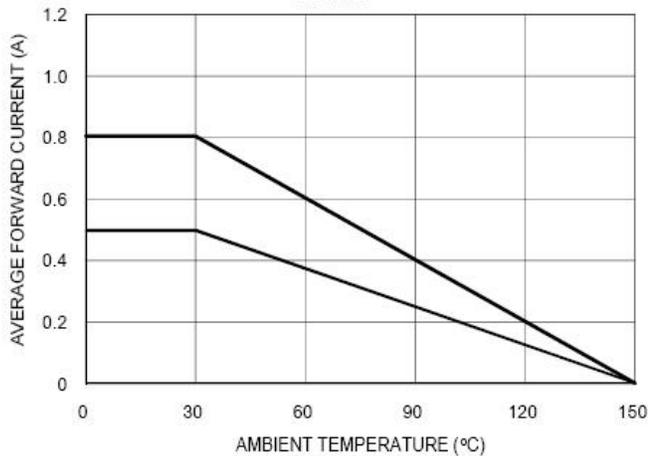


FIG. 2 TYPICAL FORWARD CHARACTERISTIC

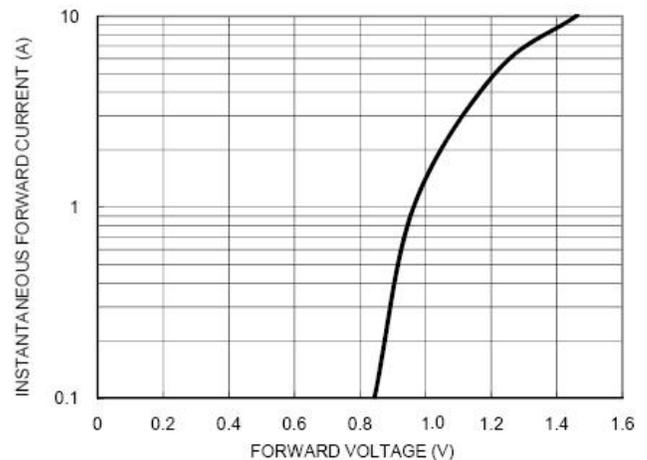


FIG. 3 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

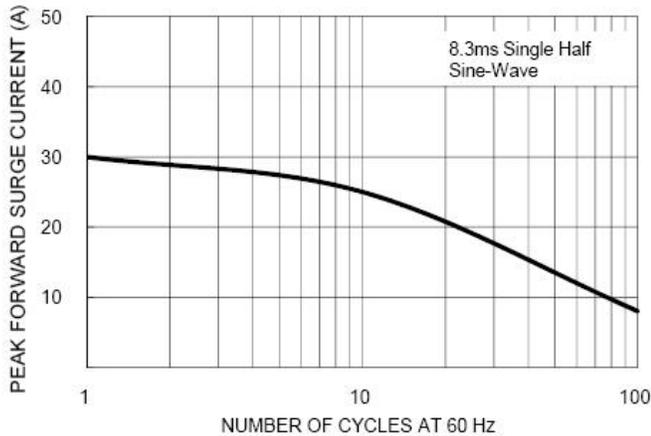
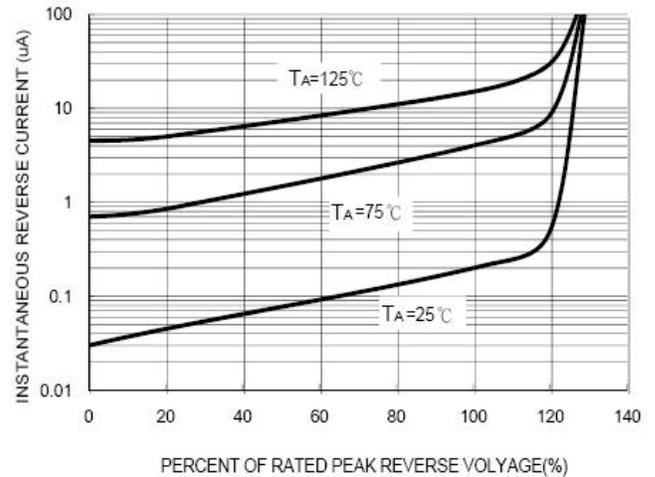
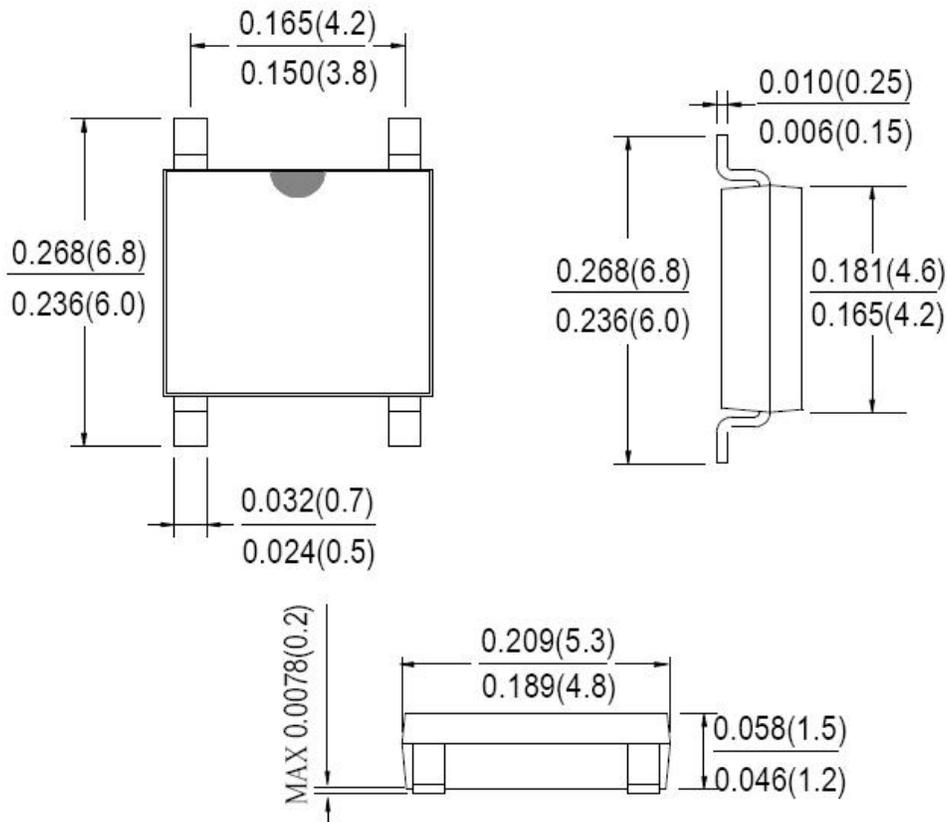


FIG. 4 TYPICAL REVERSE CHARACTERISTICS



Mechanical Dimensions ABS(Inches/Millimeters)

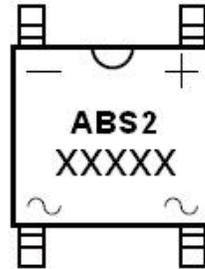


Ordering Information

Device	Package	Shipping
ABS2 THRU ABS10	ABS (Pb-Free)	5000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram

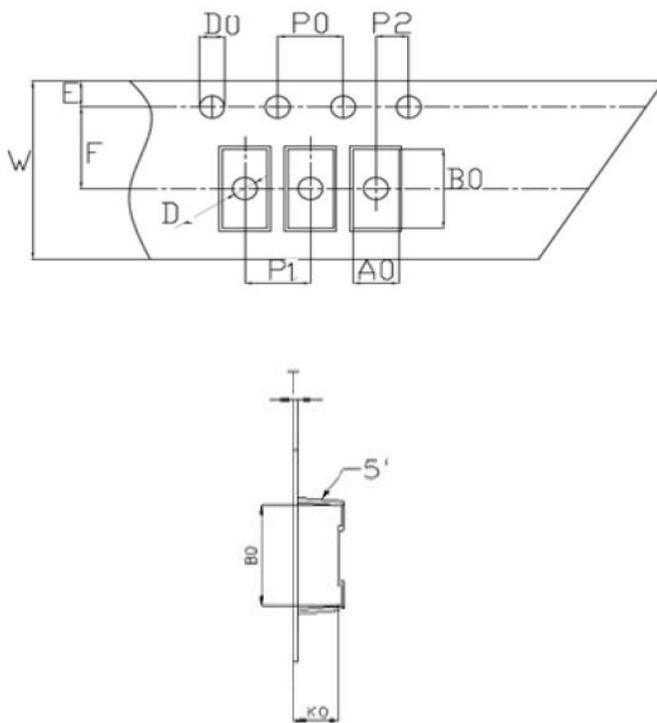


Where XXXXX is YYWWL

ABS2 = Type Number
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

Carrier Tape Specification ABS



SYMBOL	Millimeters	
	Min.	Max.
A0	5.21	5.41
B0	7.10	7.30
D0	1.50	1.60
D1	1.40	1.60
P0	3.90	4.10
P1	7.90	8.10
P2	1.95	2.05
E	1.65	1.85
K0	1.55	1.75
F	5.45	5.55
W	11.90	12.10
T	0.24	0.30
10P0	39.80	40.20

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